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**(54) ANISOTROPICALLY CONDUCTIVE ADHESIVE COMPOSITION, METHOD FOR CONNECTING CIRCUIT TERMINAL AND CONNECTION STRUCTURE OF THE CIRCUIT TERMINAL**

(57)Abstract:

**PROBLEM TO BE SOLVED:** To obtain an anisotropically conductive adhesive composition capable of preventing corrosion of metal patterns at a connection part and provide a method for connecting circuit terminals by using the same and provide a connection structure.

**SOLUTION:** This anisotropically conductive adhesive composition uses an adhesive which is put between opposed circuit electrodes and electrically connects the electrodes in a charged direction by charging the opposed circuit electrodes and comprises (1) an epoxy resin, (2) a latent curing agent, (3) a phenoxy resin having an aromatic cyclic structure containing  $\geq 2$  benzene rings as a film-forming material and (4) electroconductive particles as essential components. This method for connecting circuit terminals is to arrange a first circuit material having a first connecting terminal and a second circuit material having a second connecting terminal to face

the first connecting terminal to the second terminal, put the aforesaid anisotropically conductive adhesive composition between the oppositely arranged aforesaid first connecting terminal and the second connecting terminal and electrically connect the oppositely arranged aforesaid first terminal with the second connecting terminal by heating under pressure.

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